

Man Portable Fanless Embedded System



ELECTRONIC

- Collaborative engineering approach with the customer
- Signal Integrity considerations
- Power distribution
- motherboard design
- Power conversion
- EMC filtering
- RF Shielding

THERMAL

- Simulation
- Design of fin spacing, orientation and height for optimal heat dissipation
- Internal thermal layout considerations
- Selection of Materials and manufacturing techniques for best thermal path versus design for manufacture

MECHANICAL

- Optimised for low weight versus Thermal performance
- Packaging a combination of bespoke and COTS modules
- RF and EMC separation features
- Rugged design to meet Mil-Std-810F for shock and vibration requirements
- IP67 sealing



PRODUCTION

- Volume production
- Design for manufacture
- Modular design
- HASS
- ESS
- Product Acceptance Testing
- Software programming



QUALIFICATION

- Full qualification program
- Thermal cycling
- Shock and Vibration
- Moisture ingress/sealing
- Solar radiation
- EMC
- First Article inspection in accordance with AS9100